

Highlights

Excellent Quality and Superior Service

- ▶ All Wire Bond Counts
- ▶ All Body Sizes
- ▶ All Ball Configurations & Ball Sizes
- ▶ <45µm Pad Pitch
- ▶ Less Than 1-day Turn
- ▶ Open Cavity
- ▶ Customer Supplied Substrates
- ▶ CORWIL Supplied Substrates

CORWIL has established itself as the premier quick-turn IC assembly subcontractor for BGA packages. When **time-to-market** is critical to grab market share and maximize profits of your new products, CORWIL will help you achieve your goals. CORWIL can produce your prototype units in **less than one day**. CORWIL was one of the first subcontractors to produce BGAs in the Silicon Valley and has remained at the leading edge of BGA assembly technology.

- Fine pitch wire bonding with the latest state-of-the-art world class wire bonders: 45µm in production, <45µm prototype, 35/70µm staggered. All wire counts and ball configurations can be assembled. Ball sizes as small as 10 mils (.25 mm).
- Quick-turn prototype quantities or pre-production volumes. CORWIL will build enough samples to make all of your customers happy.
- CORWIL will use your existing BGA substrates, in either singulated or strip form. Substrates can be plastic laminate PBGA, thermally enhanced metal based (cavity up or down) or special multiple dice per unit configurations.
- Sealing methods vary to meet your requirements: epoxy dam & fill, transfer mold (in 27 and 35 mm sizes), and open cavity to allow you to probe and/or FIB your new die.
- CORWIL can coordinate substrate design and fabrication in BT laminate material through reliable industry sources.
- CORWIL has built its reputation providing customers with:
excellent quality and superior service

Contact Us At:

CORWIL Technology Corporation
1635 McCarthy Boulevard
Milpitas, CA 95035-7415
Phone: 408-321-6404
Fax: 408-321-6407
E-mail: info@corwil.com
Web: <http://www.corwil.com>



DSCC QML Listed
(Qualified Manufacturers List)
MIL-STD-883 DSCC Suitability